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Part Number:

0736590004

Status:

Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 12 Circuits, Gold (Au) 0.76µm (30µ")

Documents:

[3D Model](#)

[Drawing \(PDF\)](#)

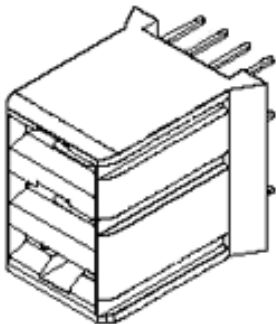
[RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family	Backplane Connectors
Series	73659
Application	Backplane
Comments	Midplane Power Module
Component Type	Power Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	12
Circuits (maximum)	12
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	150
Plating min: Termination (µm)	3.75
Polarized to PCB	No
Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole



Series

image - Reference only

EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

73659Series

Mates With

73651 HDM® Board-to-Board Daughterboard Power Module

Electrical

Current - Maximum per Contact	15A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	38
Shielded	Yes
Voltage - Maximum	500V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	Reflow Capable (SMT only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0819
Sales Drawing	SDA-73659-000*

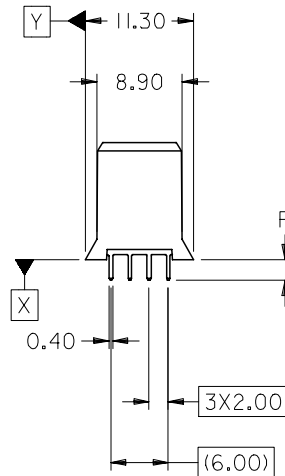
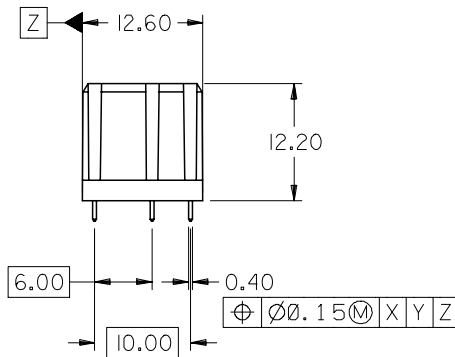
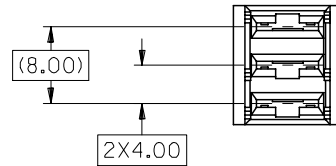
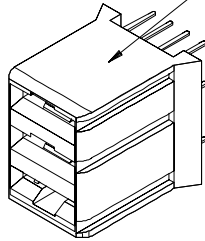
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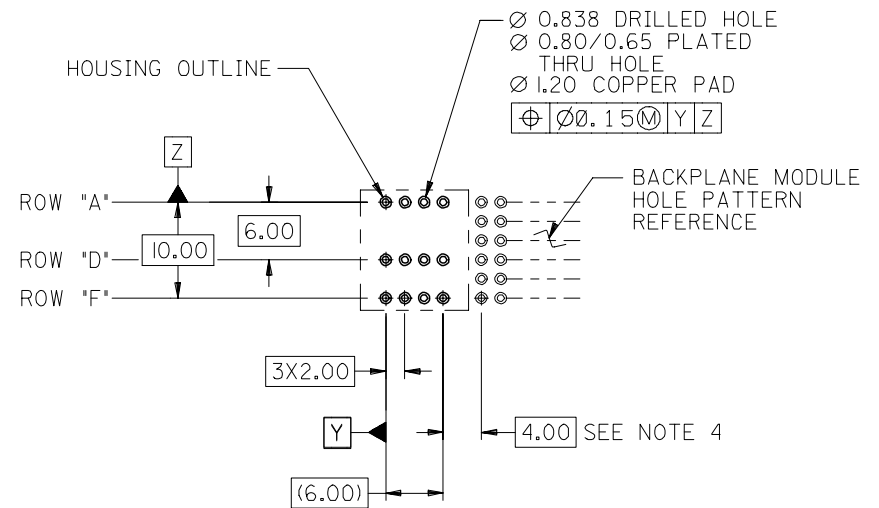
MATERIAL NUMBER	DIM "P" ± 0.25
73659-0001	2.00
73659-0002	2.50
73659-0003	3.00
73659-0004	3.50

DATE CODE AND
PART NUMBER ON
THIS SURFACE OR
SURFACE OPPOSITE.



NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK
TERMINAL - BERYLLIUM COPPER
2. FINISH:
0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. THIS DIMENSION MUST BE A MULTIPLE OF 4.00mm.
5. DIMENSION ARE IN MILLIMETERS.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 1.57 MIN

REV	DESCRIPTION
1	MODIFY FINISH
2	EC NO: UCP2007-2259
3	DRWN:MSI BARRA 2007/03/13
4	CHKD:BBARKER 2007/03/21
5	APPR:SMILLER 2007/03/22

QUALITY SYMBOLS
$\nabla = 0$
$\nabla = 0$

GENERAL TOLERANCES (UNLESS SPECIFIED)		
	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.10	± ---
1 PLACE	± 0.25	± ---
ANGULAR ± 1/2°		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE	MM ONLY
DRAWN BY	REED
DATE	1996/12/10
CHECKED BY	BINGHAM
DATE	1996/12/10
APPROVED BY	BIXLER
DATE	1996/12/10
MATERIAL NO.	SEE TABLE
SIZE	B

SCALE	2:1
DESIGN UNITS	METRIC
THIRD ANGLE PROJECTION	$\odot$
SALES ASSY HDM BACKPLANE POWER MODULE WITH SOLDER TAILS	
MOLEX INCORPORATED	
DOCUMENT NO.	SDA-73659-000*
SHEET NO.	1 OF 1

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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